

NOV 24 2006

Amendments to the Specification:

Please make the following amendments to the specification. Material to be inserted is in **bold and underline**, and material to be deleted is in ~~strikeout~~ or (if the deletion is of five or fewer consecutive characters or would be difficult to see) in double brackets [[]].

Please replace the paragraph found on page 11, line 21, to page 12, line 2, of the application, with the following replacement paragraph:

Fig. 5 shows a bottom view of selected portions of sorter assembly 112 of sorting device 150. The sorter assembly may include a substrate 180 having a plurality of thin-film electrical devices 140. The sorter assembly also may include a plurality of sorter units 182, delineated here generally as a three-by-three array of dashed boxes. The substrate may define a plurality of openings, such as feed holes 184, through which fluid and particles may pass, to and/or from the adjacent manifold 120 (see Fig. 4). Feed holes 184 may be arranged in columns, shown at 185. Each column 185 may be aligned with a first-layer manifold conduit, such as as [[a]] conduits ~~186a-186e~~ 186a-186d, which are shown in dashed outline and disposed adjacent an opposing surface of the substrate. Manifold conduits are described in more detail in relation to Figs. 7-9. A fluid barrier that cooperates with the substrate to form channels is disposed adjacent the substrate but is shown elsewhere (see Figs. 6 and 7).

Page 2 - AMENDMENT
Serial No. 10/763,112
HP Docket No. 200301164-1
KH Docket No. HPCC 3B2

NOV 24 2006

Please replace the paragraph found on page 13, line 24, to page 14, line 5, of the application, with the following replacement paragraph:

Substrate assembly 112 may include substrate 180, thin-film layers 244 formed adjacent the substrate's surface (in or on the substrate), and fluid barrier 196 connected to the substrate and thin-film layers. The thin-film layers may define electrical portion 136 of the substrate assembly, particularly thin-film electrical devices 140 thereof. Fluid barrier 196 may be formed unitarily or, as shown in the present illustration, may be formed of a channel layer 246, and a cover layer 248. The channel layer may define walls 250 of channel 198. Channel layer 246 may be formed from any suitable material, including, but not limited to, a negative or positive photoresist (such as SU-8 or PLP), a polyimide, a dry film (such as DUPONT Riston® ~~DuPont Riston~~), and/or a glass. Methods for patterning the channel layer 246 may include photolithography, micromachining, molding, stamping, laser etching, and/or the like. Cover layer 248 also may define a wall of channel 198. The cover layer may be formed of an optically transparent material, such as glass or plastic, to permit light from the light source to enter channel 198.

Page 3 - AMENDMENT
Serial No. 10/763,112
HP Docket No. 200301164-1
KH Docket No. HPCC 3B2